

MPI Corporation 6223.TT

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Presentation Disclaimer

The information herein contains forward-looking statements. We have based these forward-looking statements on our current expectations and projections about future events. Although we believe that these expectations and projections are reasonable, such forward-looking statements are inherently subject to risks, uncertainties and assumptions about us, including, among other things: the intensely competitive Semi-conductor, and LED industries and markets; Cyclical nature of the semiconductor industry; Risks associated with global business activities; General economic and political conditions. All financial figures discussed herein are prepared pursuant to IFRS. All audited figures will be publicly announced upon the completion of our audited process.

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MPI Divisions

Since 1995

Probe Card

Since 2001

Photonics Automation

Since 2014

Advanced Semiconductor Test

Since 2015

Thermal Test

Since 2021

Celadon Systems

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MPI Global Presence

MPI AMERICA

MPI CELADON

MPI SUZHOU

MPI CORPORATION

MPI Offices

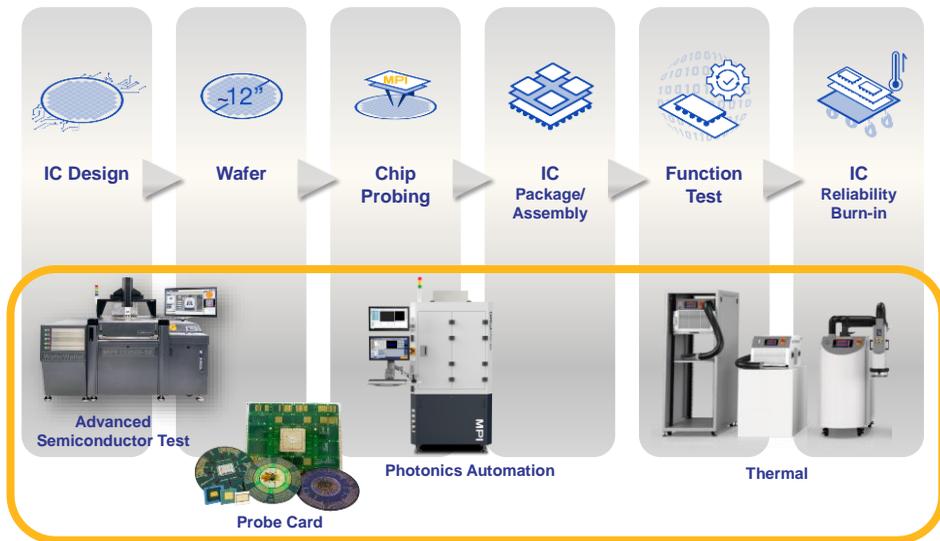
MPI Representatives

MPI Locations

Worldwide				Taiwan			
MPI America CA, USA (2017)	MPI Suzhou Jiangsu, CN (2017)	Celadon Systems MN, USA (2021)	Headquarters Hsinchu, TW (2000)	Luzhu Office Kaohsiung, TW (2006)	2 nd Production Site Hsinchu, TW (2012)	Xingpu Office Hsinchu, TW (2014)	3 rd Production Site Hsinchu, TW (2021)

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MPI-The Powerhouse of Testing Solutions



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Agenda



Business Contents

- Probe Card
- Photonics Automation
- Thermal & AST



Financial Statements

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MPI CORPORATION

Probe Card

READY FOR THE TEST™

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MPI Probe Card

Advanced Wafer Sort Test Solutions

Vertical / MEMS

Cantilever



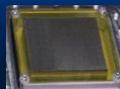
Features



Fine Pitch



MEMS



High Pin Count



High Speed



Substrate



Hand-wired



RF

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MPI Probe Card Full range of products for the applications sufficient coverage solutions to IC markets Company Confidential C

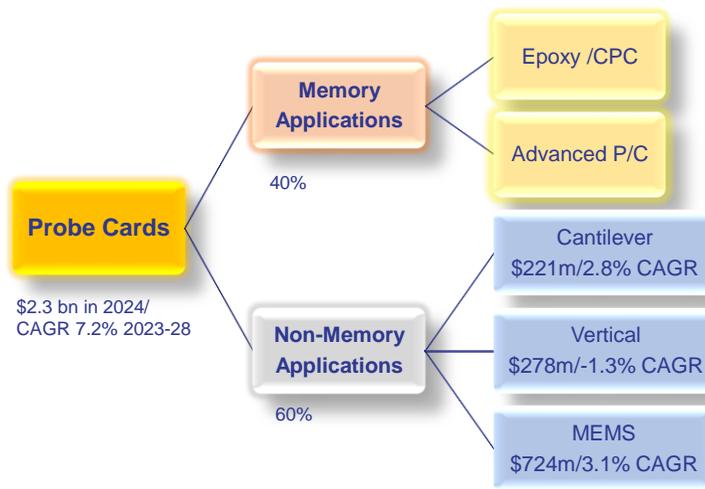
CPC	OSPREY (FW)	KESTREL (MW)	EVS/FCB
Pitch 40um (Logic) or more Pitch 7um (Display Driver) or more	Pitch 40um or more Small pad size	Pitch 70um or more Low force & High pin count	Pitch 80um or more High CCC

Technology	28nm	40nm	55nm	10nm	28nm	28nm	7nm	28nm	40nm	40nm	3nm	5nm	7nm	3nm	5nm	7nm	10nm	3nm	5nm	7nm	
COF / COG	●	●																			
Wire-Bond																					
Soldering Bumps																					
Cu-Pillar Bumps																					
COWOs																					

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Global Probe Card Market Update

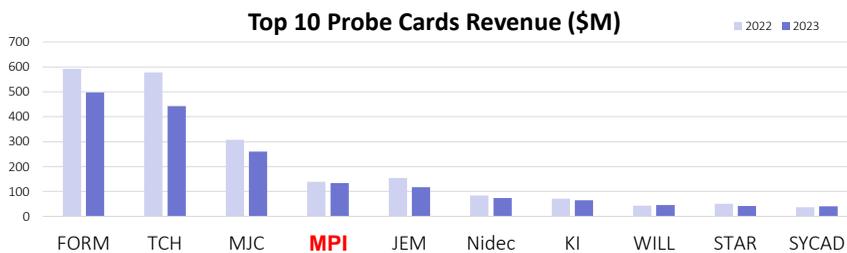


Source: TechnInsights

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Total Own Make IC Probe Cards Vendors

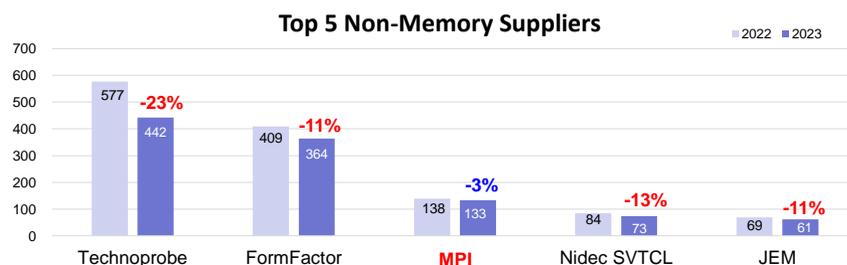
	(Rank)		2020	2021	2022	2023
FormFactor		USA	1	1	1	1
Technoprobe		Italy	2	2	2	2
Micronics Japan		Japan	3	3	3	3
MPI Corporation		Taiwan	5	5	5	4
Japan Electronic Materials		Japan	4	4	4	5



Source: Technights

Top 5 Non-Memory Probe Card Vendors

	(Rank)		2018	2019	2020	2021	2022	2023
Technoprobe		Italy	2	2	2	1	1	1
FormFactor, Inc.		USA	1	1	1	2	2	2
MPI Corporation		Taiwan	3	3	3	3	3	3
Japan Electronic Materials		Japan	4	5	5	4	5	5
Nidec SVTCL		Singapore	5	4	4	5	4	4



Source: Technights

Probe Card: Total Solution Provider

- **Comprehensive Product Range for Circuit Testing**

全方位的產品布局

MPI provides omnidirectional products to global customers, including fine pitch CPC, high speed VPC and low force MEMS solutions.

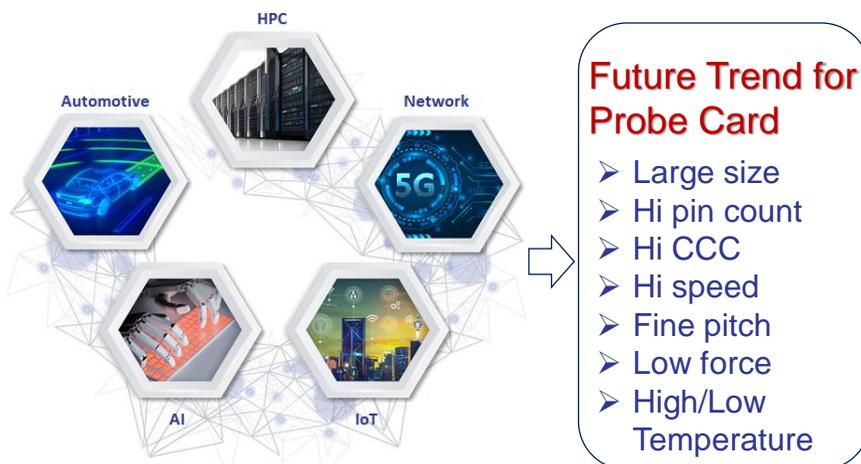
- **Solid Global Clientele** 堅實的國際合作夥伴

MPI works closely with worldwide market leaders, especially for the AI, HPC application related.

- **Complete Probe Card Solution** 完整的探針卡整合方案

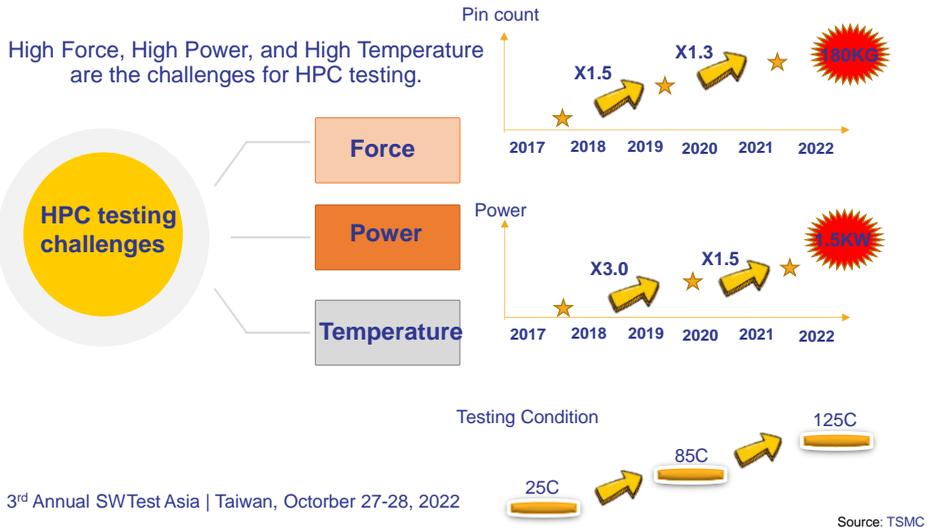
Provide probe head, substrate(MLO/MLC/MLOC) and PCB one-stop service.

Fast Growing Applications



Source: TSMC

HPC Challenges



Interface Technical Complexity Check in

Complexity Trends are on pace to be at 2022 targets (1 Cycle) or in some cases beyond

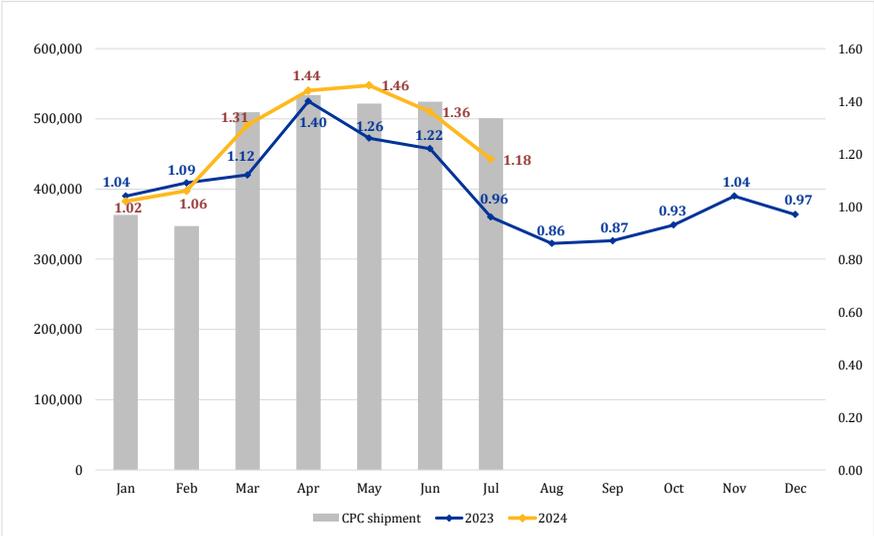
“2x4 Scaling”=2xPins, 2xPerformance, every 4 years



		2018	2022	2026
		Level 4	Level 5	Level 6
Pin Density	Pin Pitch	90um	70um	50um
	Total Contact Force	80kg	150kg	250kg
I/O Speed	Digital	32Gpbs	64Gpbs	128Gpbs
	RF/mmWave	< 12 GHz	29 GHz	+60 GHz
Device Power	Main Power	900 mV	750mV	625mV
	Single Rail	35A	50A	100A
	Impedance	2.2 mOhm	1.4 mOhm	0.8 mOhm
Thermal	Self Heating	75 W		
	Operating Range	0 to +80C	0 to +105C	20 to +125C
Most Expensive Probe Card		\$400K*	>\$500K	>\$700K

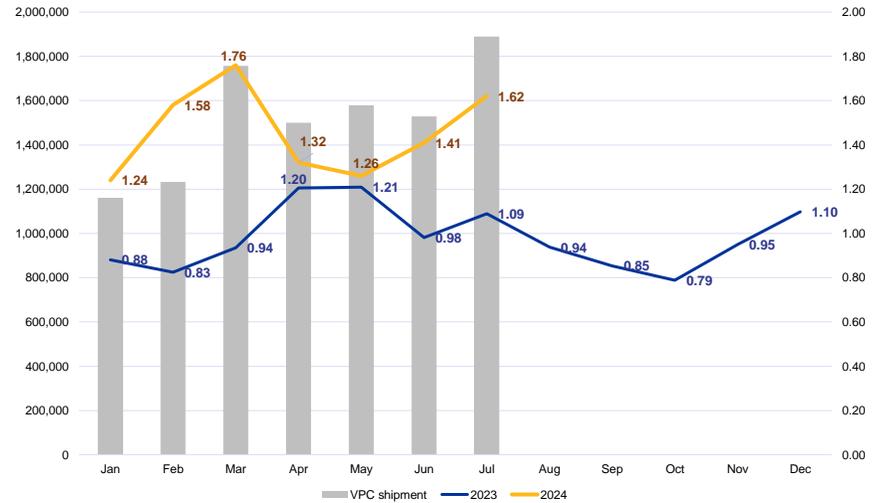
Source:Teradyne

CPC Pin-Shipment & BB ratio



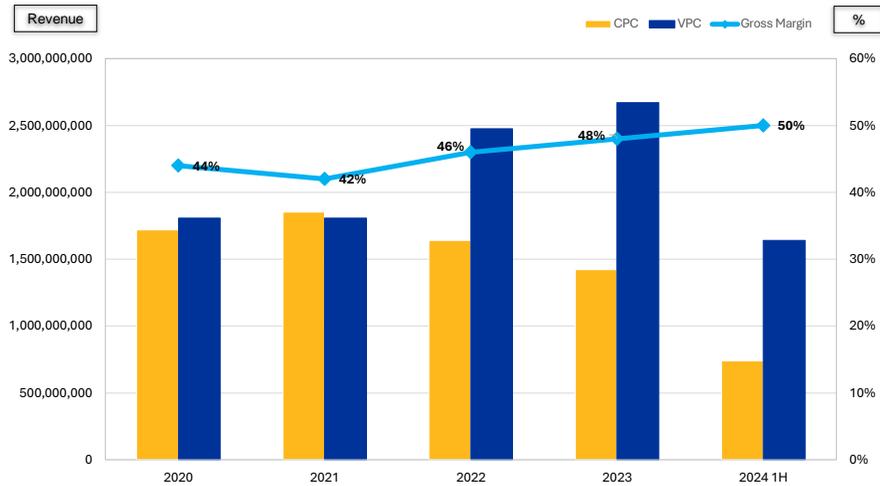
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VPC Pin-Shipment & BB ratio

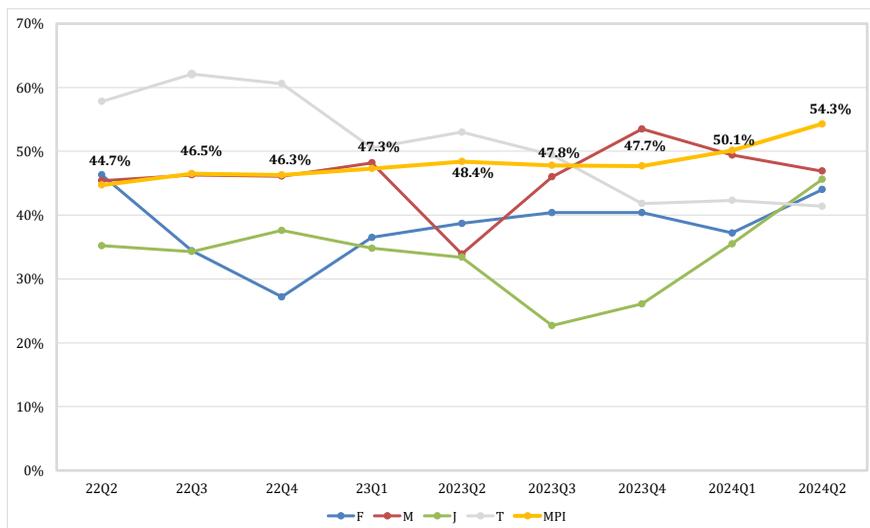


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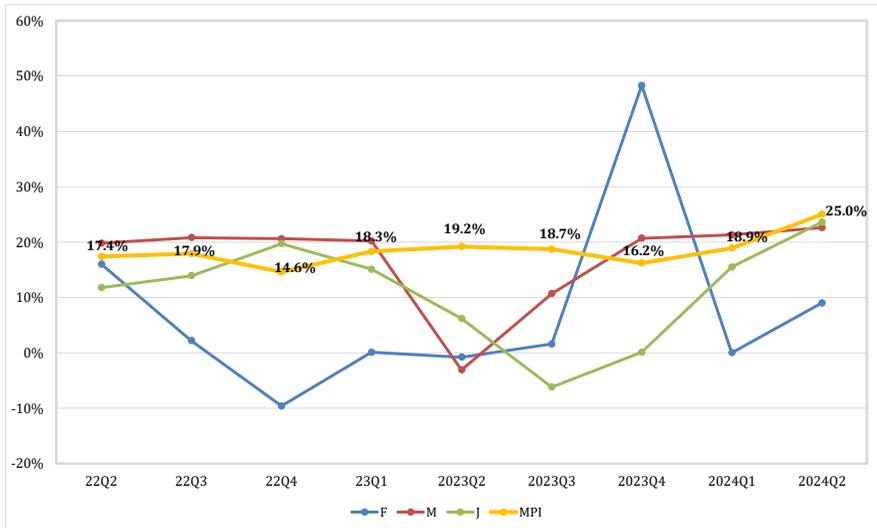
CPC and VPC Yearly Status



Gross Margin Between Global Peers



Operating Margin Between Global Peers



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MPI Probe Card

Company Confidential

Our Customer

The MPI is committing more than 800 customers globally to contribute to industrial development as well as providing testing industry advanced technology needs.

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Photonics Automation

READY FOR THE TEST™

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Product Portfolio and Capability



VEGA Line
Optical Sensing

AVIOR Line
Optical Communications

CAPELLA Line
LED/ Mini LED

GEMINI Line
Micro Display

- **High Power VCSEL Wafer Testing**
Wafer / Board Prober Development
Testing methodology Development
- **High Power VCSEL PKG Testing**
PKG Handler Development
Testing methodology Development
- **VCSEL / Photo-Detector Testing**
Wafer / Board Prober Development
Testing methodology Development
- **RF Character**
Wafer Level RF Testing Integration
- **SiPh Die/PKG Platform**
SiPh Handler Development
- **uLED Mass Production Methodology**
Wafer prober for large quantity die testing method
- **Panel testing platform development**
Panel / Panel in-process testing platform

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Development Plan by Application



Optical Sensing	Optical Communications	Micro Display
<ul style="list-style-type: none"> ➢ Focus on Sensing VCSEL Testing ➢ Production Wafer Prober in Low Temperature ➢ High Power Measurement Tool and Technology Development ➢ Flip Chip Wafer VCSEL testing Solution ➢ Package / Hybrid Device testing tool 	<ul style="list-style-type: none"> ➢ Focus on VCSEL/Photodetector Testing ➢ Wafer Prober for Dark / Responsivity / Capacity measurement ➢ RF Measurement Capability Development ➢ SiPh package testing approaching 	<ul style="list-style-type: none"> ➢ Lab and production wafer testing tool development ➢ Contacting Accuracy Improvement ➢ Innovative testing methodology ➢ Optical measurement in production methodology

PA: Work With Market Leaders

- **Value Enhanced Product Lines** 客戶價值導向的產品線規劃

MPI's experienced RD team comes across lighting and electrical fields with automation core technology that enables us to develop leading market solutions ie VCSEL & Micro LED.

- **Solid Global Clientele** 穩固的全球客戶群

MPI works closely with market leaders and international brand names for most advanced testing solutions.

- **Continuous Product Innovation** 持續的產品創新

Non stop RD investments helps MPI to provide high value added products that tackles clients' testing bottleneck.

MPI CORPORATION

Thermal/AST

READY FOR THE TEST™

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MPI Thermal
Hot and Cold Air Flow
Environmental Temperature Test

-100°C  +300°C
ThermalAir Series
Temperature Testing Systems

Applications & Industry Segments

- Semiconductor
- Automotive
- Aerospace
- Telecommunications
- Fiber Optic
- Electronics
- Sensors
- Advanced Technology

The advertisement features a row of seven different MPI Thermal testing units, ranging from compact benchtop models to larger industrial floor-standing units. Each unit is shown with its associated test fixtures and cables. The background is a dark blue gradient with light streaks, and the overall design is clean and professional.

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Thermal: Customer Focus

- **Innovational Temperature System** 創新的溫度測試系統

Ongoing R&D investments in platforms and improvements leads MPI to meet customer demands. Thermal systems have a number of patents to provide efficient energy saving products that helps clients to fulfill ESG responsibility.

- **Top Skillful RD Team** 頂尖優秀專業的研發團隊

MPI's thermal solutions are developed by industry veterans with over 100 years of combined experience.

- **Deep Cooperation with Leading Customers for Engineering and Production demand**

與世界領導級大廠深度合作, 提供工程及量產需求

Product application expands to automotive , 5G/RF communication , fiber optic , and sensing fields.

MPI Advanced Semiconductor Test

Engineering Probe Systems
and
RF Probe Products

50 – 300 mm

26 – 110 GHz

Applications & Industry Segments

- Device Characterization
- High Power
- RF & mmW
- Design Validation
- Failure Analysis
- Wafer Level Reliability
- Silicon Photonics
- Laser Cutter

AST: Unique Market Leader

- **Unique Global Position** 全球獨特的市場地位

Combining Analytical probing solution and RF measurement core technology , MPI is top solution provider for full range hi-frequency response measurement.

- **VOC Design** 客戶導向設計

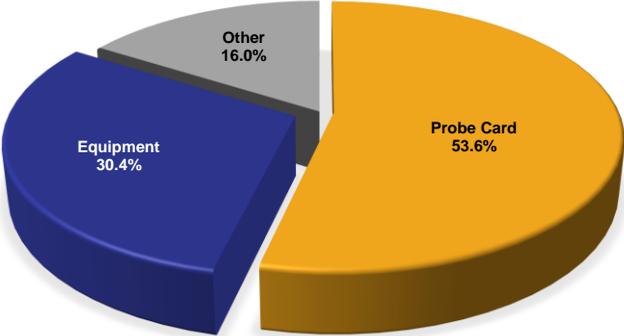
Design based on Voice of the customer to full-fill customers' needs.

- **Complete Solution** 提供完整的解決方案

Various series of products to cover wide range applications include Device Modeling, RF & mmW, WLR, High-Power, Failure Analysis, Extreme temperature test ...etc.

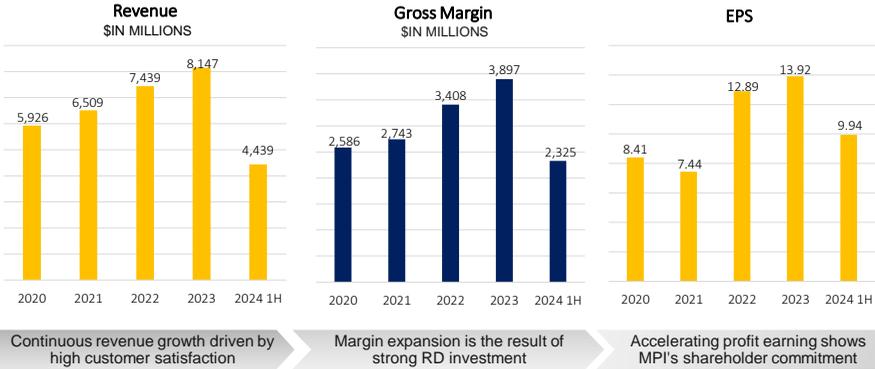
Financial Statements

2024 1H Revenue Breakdown



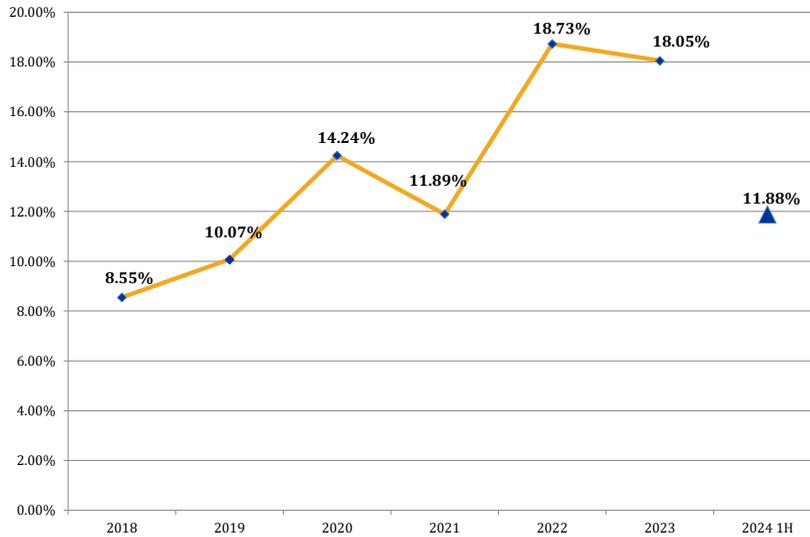
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Solid Performance



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ROE



Balance Sheet Highlight

NT\$ Million	1H 2024		1H 2023	
Cash and Cash Equivalents	2,673	20%	1,993	17%
Fixed Assets	5,913	43%	5,396	46%
Total Assets	13,697	100%	11,765	100%
LT Debt	1,403	10%	953	8%
Shareholders' Equity	8,196	60%	6,924	59%
EBITDA	1,166	26%	739	19%

*EBITDA=operating income + depreciation & amortization expenses

P&L

NT\$Million	1H 2024		1H 2023	
Net Sales	4,439,686	100%	3,796,614	100%
Cost of Goods Sold	2,113,749	48%	1,973,971	52%
Gross Profit	2,325,937	52%	1,822,643	48%
Operating Expense	1,341,566	30%	1,106,169	29%
Operating Income	984,371	22%	716,474	19%
Investment Income & Others	182,244		22,557	
Net Income (after tax)	935,601	21%	622,676	16%
EPS (after tax)	9.94		6.62	

